

**DESCRIPTION**

This series of surface mount PIN diodes utilize new and unique monolithic MMSM technology. The technology is a package/device integration accomplished at the wafer fabrication level. Since the cathode and anode interconnections utilize precision photolithographic techniques rather than wire bonds, parasitic package inductance is tightly controlled. The package parasitics provide smooth non-resonant functionality through 12GHz.

**KEY FEATURES**

- Tape and Reeled for Automatic Assembly
- Low Series Inductance (<0.2nH typical)
- **Low Parasitic Capacitance (0.06 pf typical)**
- **Meets All Commercial Qualification Requirements**
- **0204 Outline**
- **Very low thermal resistance**

**IMPORTANT:** For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>



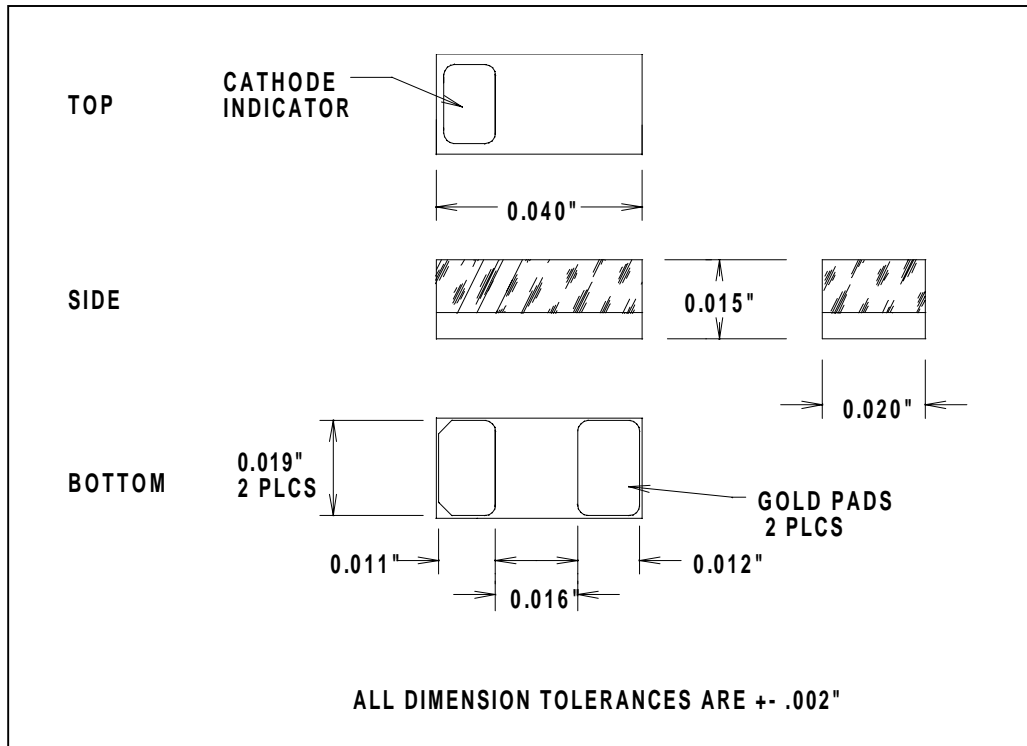
**APPLICATIONS/BENEFITS**

- **2.4 GHz PCS communications**
- **5.7 GHz Wireless LANS**
- **Solid State Switches, Attenuators, Limiters**
- **Phase Shifters**
- **Widest bandwidth of any commercial surface mounted devices**
- **Handles up to 10 watts incident RF power**
- **Ultra tight parametric distribution**

**ELECTRICAL CHARACTERISTICS**

Part #	Vb@10uA (min) Volts	Ct@10V (Max) (Pf)	Rs@10mA (max) Ohms	RS @ 20MA (Max) Ohms	Tl (Typ) Nsec	Outline Dwg Number	APPLICATION
MPP4201	70	0.20		2.5	150	206	High Power Switch
MPP4202	50	0.15		2.8	50	206	Magnetic Resonance Imaging
MPP4203	50	0.10		3.0	50	206	High Isolation Switch and Attenuator
MPP4204	25	0.15	2.0		30	206	High Speed Switch
MPL4700	25	0.15	2.0		20	206	Amplifier Protection

**DIMENSIONS**





MICROWAVE PRODUCTS DIVISION

MPP4201 – MPP4204, MPL4700

**MONOLITHIC MICROWAVE SURFACE MOUNT  
MICRO-PAK PIN DIODES**

**PRODUCT PREVIEW**

WWW.Microsemi.COM

NOTES